

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJQ10SN15S
Package Type :	SOP8

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	1.60%
Lead Frame	Cu	7440-50-8	97.43%	40.21%
	Fe	7439-89-6	2.30%	
	P	7723-14-0	0.10%	
	Zn	7440-66-6	0.15%	
	Pb	7439-92-1	0.01%	
	Silver	7440-22-4	0.01%	
Wire	Cu	7440-50-8	100.00%	0.51%
Compound	Silica Fused	60676-86-0	75.00%	56.13%
	Epoxy resin	29690-82-2	15.00%	
	Phendic Novolac	9003-35-4	5.00%	
	Antimony Trioxide	1309-64-4	3.00%	
	Carbon Black	1333-86-4	1.00%	
	Brominated Epoxy resin	68541-56-0	1.00%	
Die Attach	Silver Powder	7440-22-4	70-90%	0.59%
	Epoxy Resin	9003-36-5	5-10%	
	Diluent A	3101-60-8	1-5%	
	Diluent B	Trade Secret	1-5%	
	Diluent C	Trade Secret	1-5%	
	Hardener A	Trade Secret	1-5%	
	Hardener B	Trade Secret	1-5%	
	Solvent	Trade Secret	0.1-1%	
	Organic Peroide	Trade Secret	0.1-1%	
Plating	Tin	7440-31-5	100.00%	0.96%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.